

## EAST Search History

## EAST Search History (Prior Art)

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
S1	214	chinone.in.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2009/09/25 15:12
S2	2	S1 and (abrasive near5 compound near5 semiconductor)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2009/09/25 15:13
S3	2803	51/307.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2009/10/02 15:20
S4	4027	51/309.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2009/10/02 15:20
S5	157	(S3 S4) and (polishing or planarizing or planarization or lapping or abrading).ab. and (cerium or ceria) with (size or diameter)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2009/10/02 15:28
S6	17	(S3 S4) and ((polishing or planarizing or planarization or lapping or abrading) same (cerium or ceria) with (size or diameter) same (water or aqueous)).ab.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2009/10/02 15:45
S7	2	("20020095873").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	OFF	2009/10/02 15:47
S8	54	pasqualoni.in.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2009/10/05 11:03
S9	9380	uchino.in.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2009/10/05 11:09

S10	34	uchino.in. and polishing same (cerium or ceria)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2009/10/05 11:10
S11	12447	kido.in.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2009/10/05 11:12
S12	26	kido.in. and polishing same ceria	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2009/10/05 11:12
S13	50	yoshido.in.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2009/10/05 11:12
S14	241315	yoshida.in.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2009/10/05 11:14
S15	258	yoshida.in. and polishing same ceria	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2009/10/05 11:14
S16	68	yoshida.in. and polishing same ceria same dispersing	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2009/10/05 11:14
S17	1	dispersing near agent near5 known with polishing same (ceria or cerium)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2009/10/05 14:16
S18	2	("20030064671").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	OFF	2009/10/05 17:25
S19	1	S18 and (water or aqueous)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2009/10/05 17:25
S20	2	("20040031206").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	OFF	2009/10/05 17:31
S21	1	S20 and (water or aqueous)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2009/10/05 17:31

S22	2	("6221118").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	OFF	2009/10/05 17:50
S23	1	S22 and (water or aqueous)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2009/10/05 17:51
S24	2	S22 and (dispersant or dispersing or surfactant or surface near active)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2009/10/05 17:51
S25	2	("6478836").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	OFF	2009/10/06 08:37
S26	2	S25 and (dispersant or dispersing or surfactant or surface near active)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2009/10/06 08:37
S27	1120	106/3.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2009/10/06 08:57
S28	2807	51/307.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2009/10/06 08:58
S29	4030	51/309.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2009/10/06 08:58
S30	177	(S27 S28 S29) and (cerium near oxide or ceria) with (polishing or planarizing or planarization or lapping or abrading or CMP or chemical near mechanical) with (composition or slurry or solution or material) same water	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2009/10/06 08:58

10/ 6/ 2009 8:58:53 AM

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